SCBS220C - JUNE 1992 - REVISED MAY 1997

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16827 are noninverting 20-bit buffers composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable (10E1 and 10E2 or 2OE1 and 2OE2) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

SN54ABT16827 . . . WD PACKAGE SN74ABT16827...DL PACKAGE (TOP VIEW)

		U		L
10E1	1		56	1 <u>OE2</u>
1Y1[2		55] 1A1
1Y2[3		54] 1A2
GND[4		53	GND
1Y3[5		52] 1A3
1Y4[6		51] 1A4
V _{CC} [7		50] v _{cc}
1Y5[8		49] 1A5
1Y6[9		48] 1A6
1Y7[10		47] 1A7
GND[11		46	GND
1Y8[12		45] 1A8
1Y9[13		44] 1A9
1Y10[14		43] 1A10
2Y1[15		42] 2A1
2Y2[16		41	2A2
2Y3[17		40	2A3
GND[18		39	GND
2Y4[19		38] 2A4
2Y5[20		37] 2A5
2Y6[21		36] 2A6
V_{CC}	22		35] v _{cc}
2Y7[23		34] 2A7
2Y8[24		33] 2A8
GND[25		32	GND
2Y9[26		31] 2A9
2Y10	27		30	2 <u>A10</u>
2 0E1 [28		29	2 <u>OE2</u>

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16827 is characterized for operation over the full military temperature range of -55° C to 125 $^{\circ}$ C. The SN74ABT16827 is characterized for operation from -40°C to 85°C.



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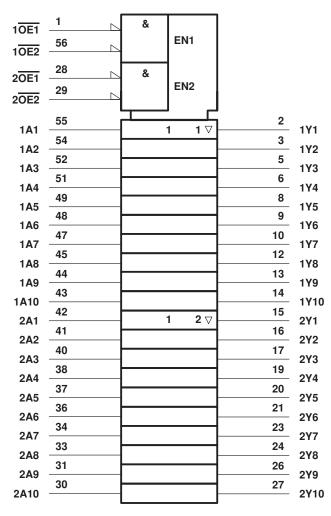


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FUNCTION TABLE (each 10-bit section)

	INPUTS		ОИТРИТ
OE1	OE2	Α	Υ
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
Х	Н	Χ	Z

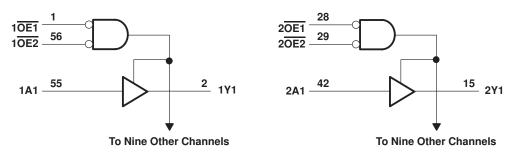
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high or power-off state, V _O	
Current into any output in the low state, IO: SN54ABT16827	96 mA
SN74ABT16827	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DL package	
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54AB1	16827	SN74AB1	16827	UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V	
loh	High-level output current		Q	–24		-32	mA
loL	Low-level output current		(5)	48		64	mA
Δt/Δν	Input transition rise or fall rate	Control pins	2	4		4	ns/V
ΔυΔν	input transition rise or fail rate	Data pins	Q.	10		10	115/ V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

SN54ABT16827, SN74ABT16827 20-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	RAMETER	TEST	ONDITIONS	Т	A = 25°C	;	SN54AB1	16827	SN74AB1	16827	UNIT	
PA	RAMEIER	l lesi c	ONDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5			
\ \/ a		$V_{CC} = 5 \text{ V}, \qquad I_{OH} = -3 \text{ mA}$					3		3		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA		0.55*				0.55	V		
V _{hys}					100						mV	
IĮ		$V_{CC} = 0$ to 5.5 $V_{I} = V_{CC}$ or GN				±1		±1		±1	μА	
lozpu‡		V _{CC} = 0 to 2.1 V _O = 0.5 V to 2	V, .7 V, OE = X			±50		±50		±50	μΑ	
l _{OZPD} ‡		V _{CC} = 2.1 V to V _O = 0.5 V to 2	0, .7 V, OE = X			±50	.0	±50		±50	μΑ	
lozh		V _{CC} = 2.1 V to V _O = 2.7 V, OE				10	2008	10		10	μΑ	
lozL		$V_{CC} = 2.1 \text{ V}_{O} \text{ to}$ $V_{O} = 0.5 \text{ V}, \overline{OE}$	5.5 V, ≥ 2 V			-10	Q	-10		-10	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	V _O = 5.5 V			50		50		50	μΑ	
IO§		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
	Outputs high	V 55V I-				2		2		2		
ICC			V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			32		32		32	mA	
	Outputs disabled	1 00 11 01				2		2		2		
ΔI_{CC} V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	mA			
Ci	$V_{l} = 2.5 \text{ V or } 0.5 \text{ V}$		5 V		3						pF	
Co		$V_0 = 2.5 \text{ V or } 0$.5 V		7.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, }	SN54AB	Г16827	SN74AB	Γ16827	UNIT
	(INFOT)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	Α	V	1	1.9	3.1	1	3.6	1	3.4	20
tPHL	A	Ť	1	2.1	3.7	1 2	4.5	1	4.2	ns
^t PZH		V	1	2.8	5	1,0	5.9	1	5.6	no
t _{PZL}	ŌĒ	Y	1	2.8	4.9	59	5.8	1	5.5	ns
^t PHZ	ŌĒ	V	2.4	4.5	6.5	2.4	6.8	2.4	6.6	ns
tPLZ	OE .	Y	1.6	3.7	5.7	1.6	7.1	1.6	6.1	

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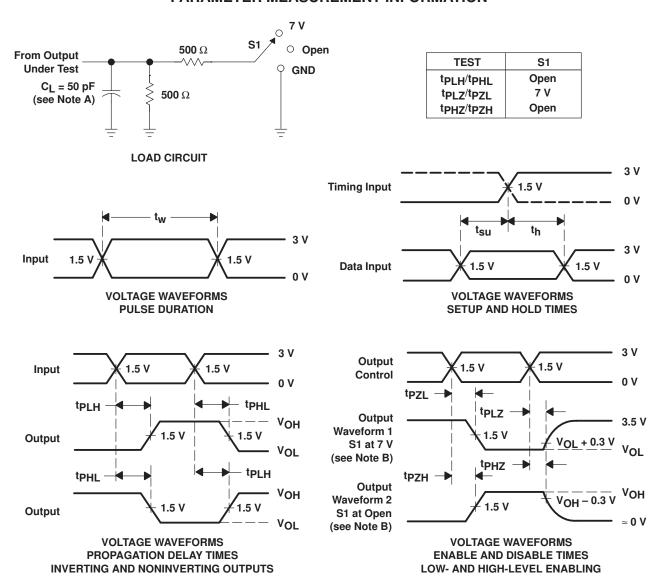
[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT16827DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16827	Samples
SN74ABT16827DLR	ACTIVE	SSOP	DL	56	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16827	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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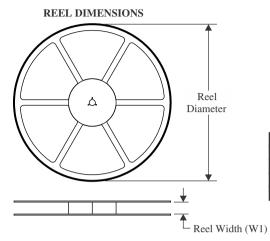
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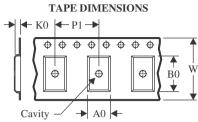
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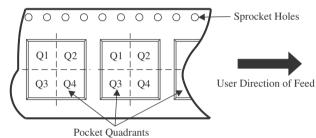
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

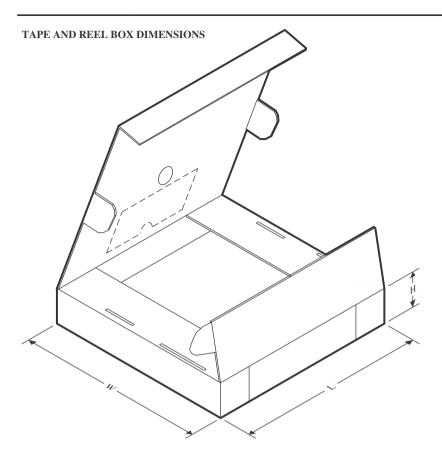


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16827DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

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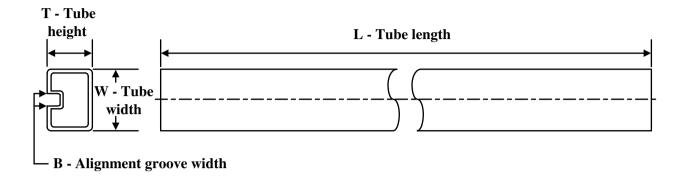
*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74ABT16827DLR	SSOP	DL	56	1000	367.0	367.0	55.0	

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TUBE

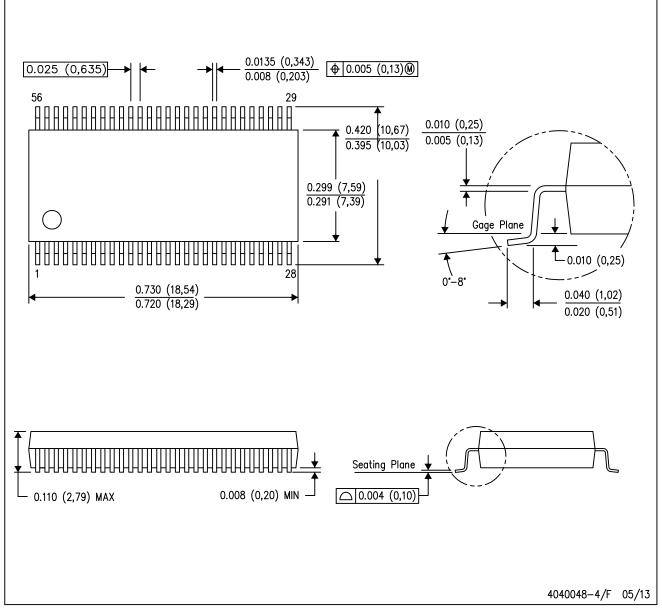


*All dimensions are nominal

Ì	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
	SN74ABT16827DL	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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